

A cross-sectional diagram of a semiconductor device assembly. A substrate 1 is shown with two mounting structures 6 and 9. Each mounting structure includes a base 7, a central core 8, and side supports 10 and 11. A component 4 is mounted on the substrate between the two mounting structures. Wires 5 connect the component 4 to pads 5a on the substrate. A frame-like structure 2 is positioned above the component, connected by vertical leads 3. An arrow A1 points towards the top right, and an arrow C1 points upwards from below the mounting structure 6.

A cross-sectional view of a semiconductor device, labeled A1. The device consists of a substrate with a central region (5) and side regions (6, 7, 8, 9, 10, 11). Arrows B1 and C1 indicate specific directions or features.

**FIG.2b**

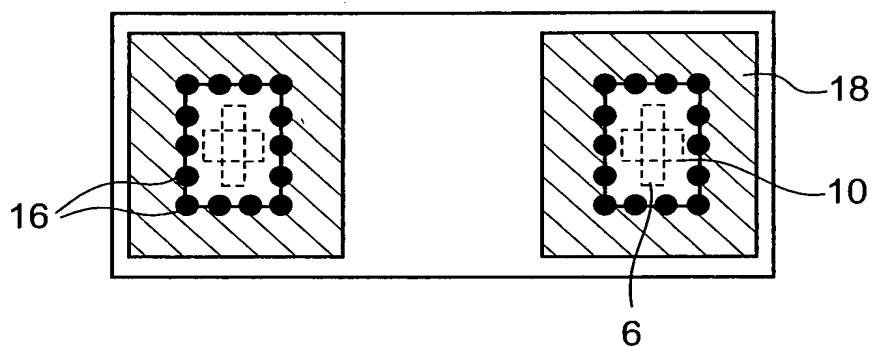


FIG.2c

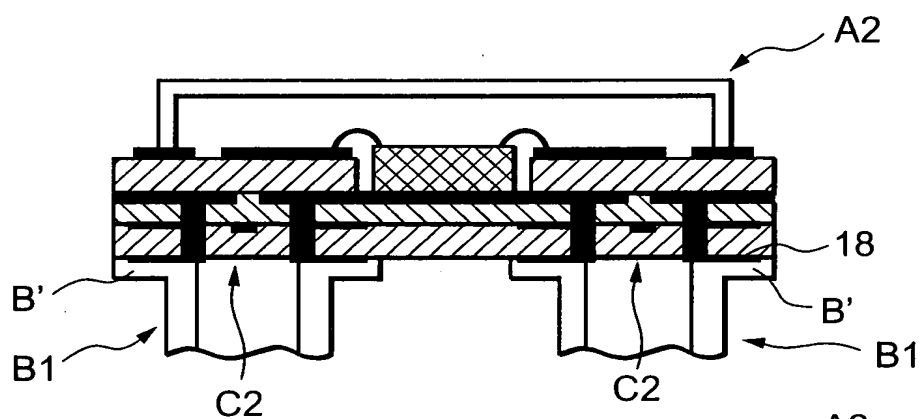
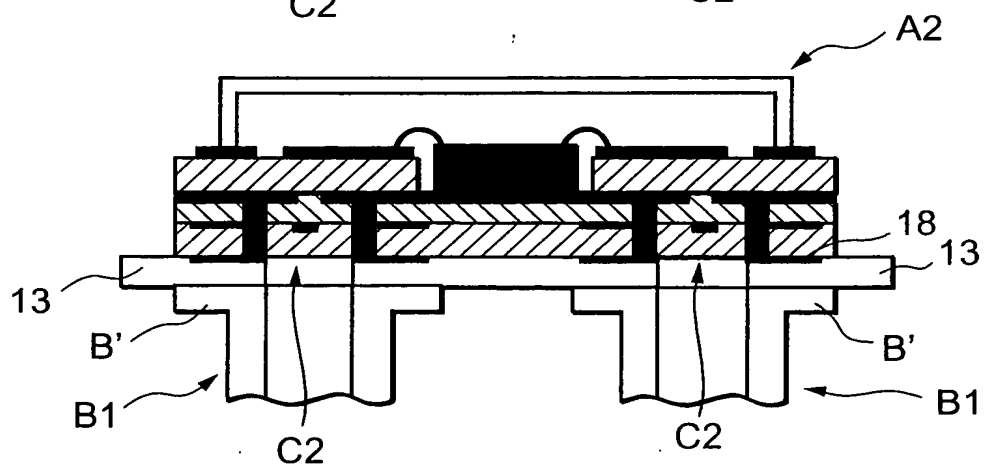


FIG. 2d



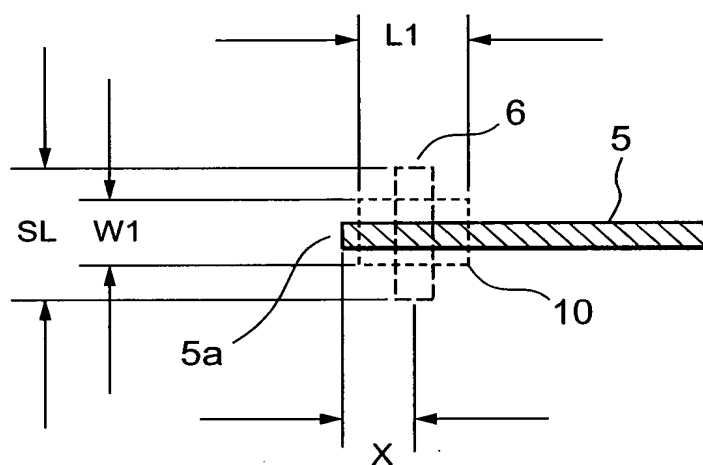
[illegible]



FIG.5

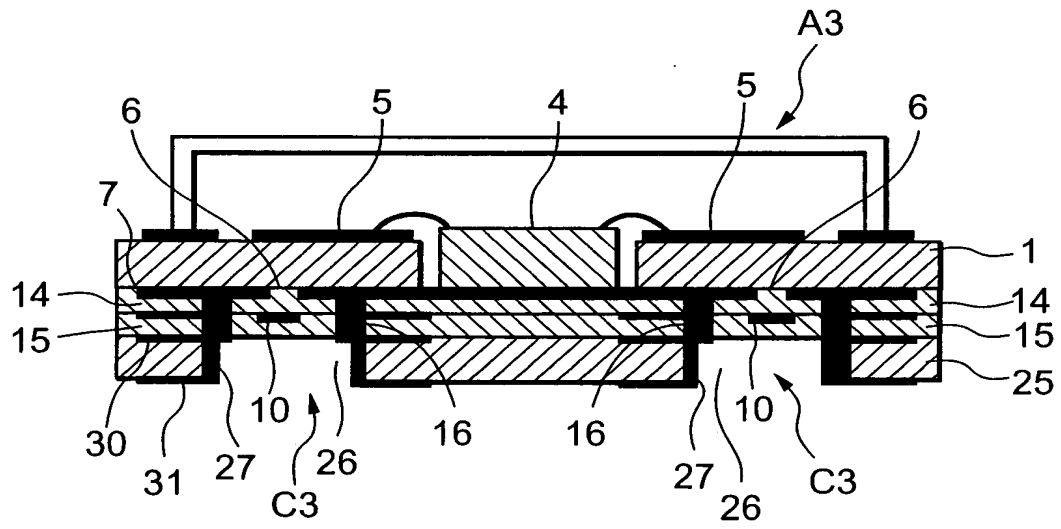


FIG. 6b

The figure consists of three parts. The top part is a cross-sectional view of a semiconductor device along line A-A'. It shows a substrate 1 with layers 14 and 15. A central layer 7 contains a patterned region 4. This region is connected via contacts 6 to a network of conductive lines 5. Below the substrate are vertical structures 10 and 11, which are part of regions B' and B1 respectively. The bottom part is a top plan view showing two square regions C2, each containing a grid of dots representing vias or contacts 16. These regions are surrounded by a frame B1. Dimension lines indicate P1, Q1, P2, and Q2.

FIG.7

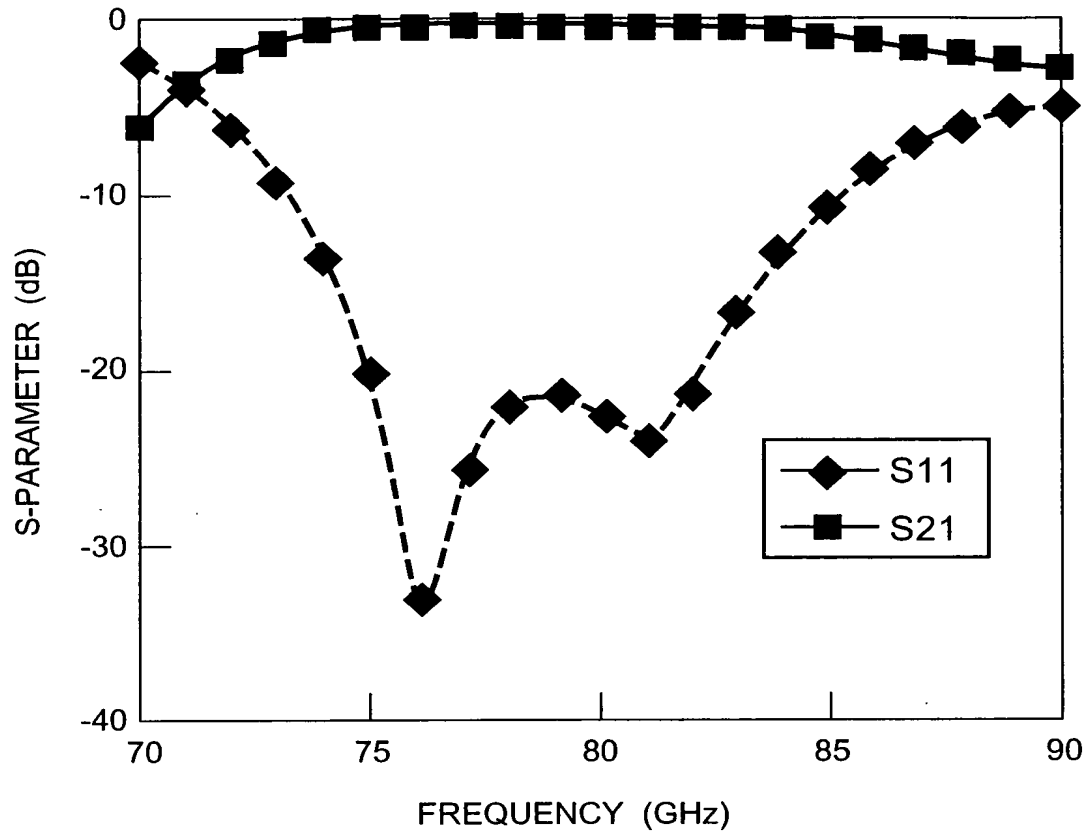


FIG.8

